

Abstract of the Disclosure

Resin particles comprised of an acrylic resin. Not only is the maximum compression deformation ratio thereof as great as 60 % or more but also the load required for 60 % compression deformation is as small as 60 mN or less. Wiring boards are therefore coupled in using an anisotropic conductive adhesive obtained by first manufacturing conductive particles having a conductive coating formed on a resin particle surface of the resin particles by adhering a conductive material to the surface of the above resin particles as a core. On dispersing the conductive particles in an adhesive material, the conductive particles sandwiched between metallic wires of the wiring boards are greatly deformed by a small load, so that the electrical devices having a high conduction reliability can be obtained.